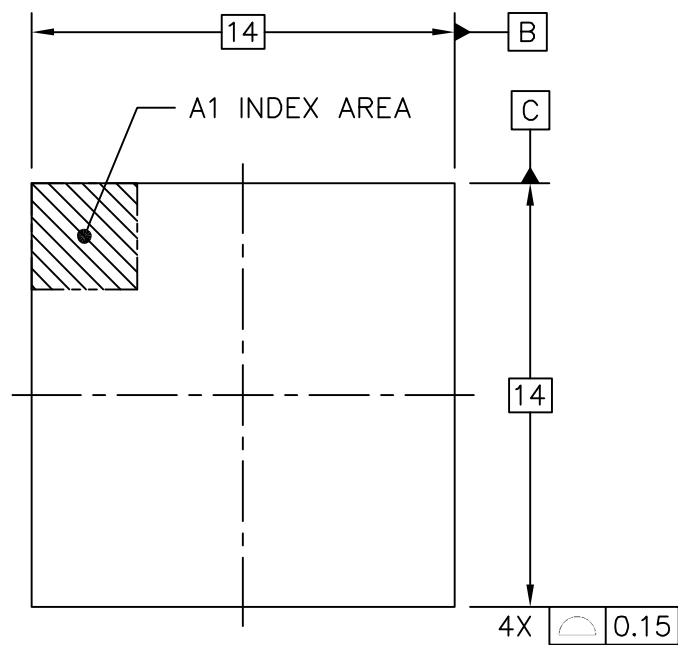
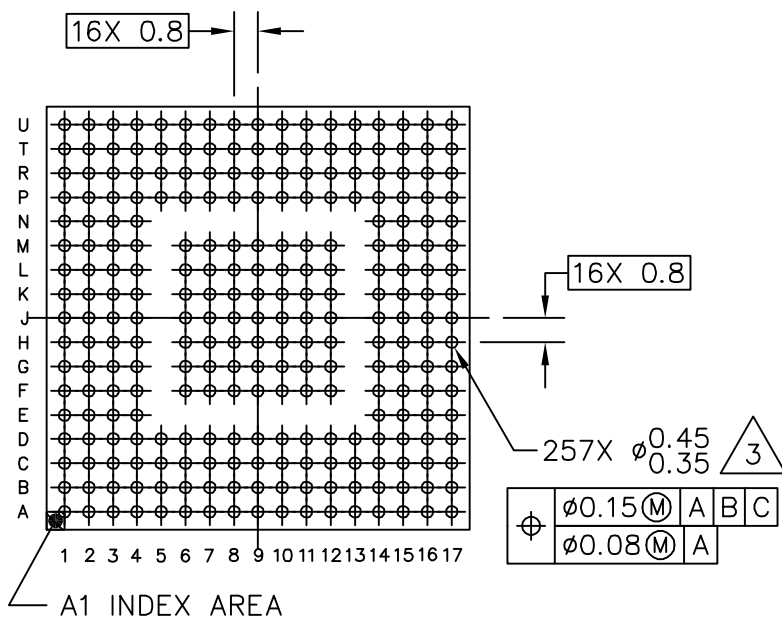
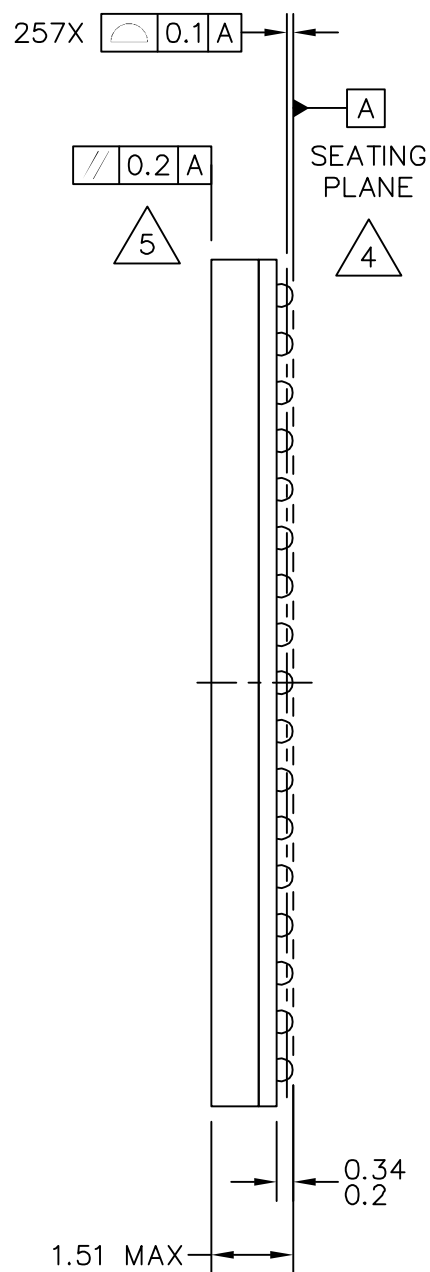




TOP VIEW



BOTTOM VIEW



SIDE VIEW

© FREESCALE SEMICONDUCTOR, INC.
ALL RIGHTS RESERVED.

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

TITLE: MAPBGA, LOW PROFILE,
14 X 14 X 1.35 PKG,
0.8 MM PITCH, 257 I/O

DOCUMENT NO: 98ASA00081D

REV: 0

CASE NUMBER: 2082-01

15 FEB 2012

STANDARD: JEDEC MO-275A-JJAC-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE:	MAPBGA, LOW PROFILE, 14 X 14 X 1.35 PKG, 0.8 MM PITCH, 257 I/O	DOCUMENT NO: 98ASA00081D		REV: 0	
		CASE NUMBER: 2082-01		15 FEB 2012	
		STANDARD: JEDEC MO-275A-JJAC-1			